

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



March 2011

FDS86140

N-Channel PowerTrench[®] MOSFET 100 V, 11.2 A, 9.8 m Ω

Features

- Max $r_{DS(on)} = 9.8 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 11.2 \text{ A}$
- Max $r_{DS(on)} = 16 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 9 \text{ A}$
- High performance trench technologh for extremely low r_{DS(on)}
- High power and current handing capability in a widely used surface mount package
- 100% UIL Tested
- RoHS Compliant

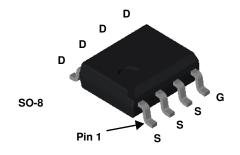


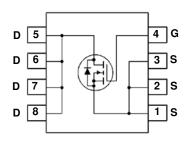
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced Power Trench® process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- DC/DC Converters and Off-Line UPS
- Distributed Power Architectures and VRMs
- Primary Swith for 24 V and 48 V Systems
- High Voltage Synchronous Rectifier





MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Paramo		Ratings	Units	
V_{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous			11.2	A
ID D	-Pulsed			50	_ A
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	264	mJ
В	Power Dissipation	T _C = 25 °C	(Note 1)	5.0	W
P_{D}	Power Dissipation $T_A = 25 ^{\circ}\text{C}$ (Note 1a)			2.5	VV
T _J , T _{STG}	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	25	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS86140	FDS86140	SO-8	13"	12 mm	2500 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter Test Conditions		Min	Тур	Max	Units
Off Chara	cteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, referenced to 25 °C		70		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	2.7	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-11		mV/°C
r _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 11.2 A		8.1	9.8	mΩ
		$V_{GS} = 6 \text{ V}, I_D = 9 \text{ A}$		10.8	16	
		$V_{GS} = 10 \text{ V, } I_{D} = 11.2 \text{ A,}$ $T_{J} = 125 ^{\circ}\text{C}$		13.1	17	
9 _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_D = 11.2 \text{ A}$		35		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 50 V V 0 V	1940	2580	pF
C _{oss}	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	440	585	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112	20	30	pF
R_{α}	Gate Resistance		0.9		Ω

Switching Characteristics

	_				
t _{d(on)}	Turn-On Delay Time		13.7	25	ns
t _r	Rise Time	V _{DD} = 50 V, I _D = 11.2 A,	5.6	11	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	23	38	ns
t _f	Fall Time		4.8	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	29	41	nC
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V} V_{DD} = 50 \text{ V},$	16.5	23	nC
Q_{gs}	Gate to Source Charge	I _D = 11.2 A	8.0		nC
Q_{gd}	Gate to Drain "Miller" Charge		6.5		nC

Drain-Source Diode Characteristics

V_{SD}	Source-Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 11.2 A (Note 2)	0.8	1.3	V
	Source-Drain Diode Forward voltage	$V_{GS} = 0 \ V, I_S = 2 \ A$ (Note 2)	0.7	1.2	
t _{rr}	Reverse Recovery Time	I _F = 11.2 A, di/dt = 100 A/μs	53	85	ns
Q _{rr}	Reverse Recovery Charge		59	94	nC

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,CA} is determined by the user's board design.



a) 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



b) 125 °C/W when mounted on a minimum pad.

^{2.} Pulse Test: Pulse Width < 300 μs , Duty cycle < 2.0%. 3. Starting T $_J$ = 25 °C, $\,$ L = 1 mH, I_{AS} = 23 A, V_{DD} = 90 V, V_{GS} = 10 V.

Typical Characteristics T_{.1} = 25 °C unless otherwise noted

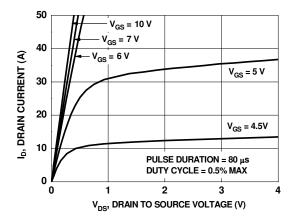


Figure 1. On Region Characteristics

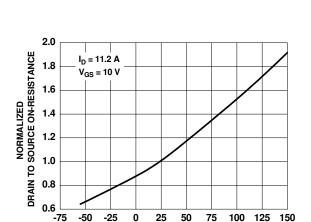


Figure 3. Normalized On Resistance vs Junction Temperature

T_J, JUNCTION TEMPERATURE (°C)

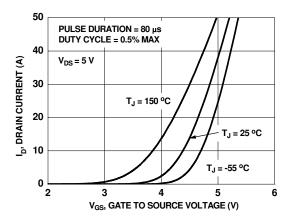


Figure 5. Transfer Characteristics

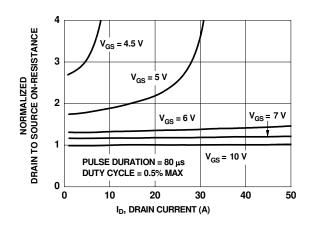


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

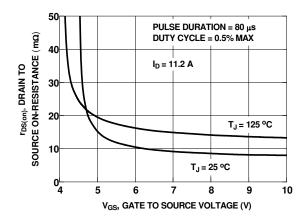


Figure 4. On-Resistance vs Gate to Source Voltage

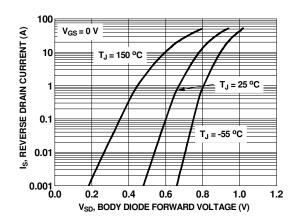


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted

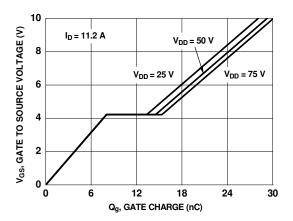
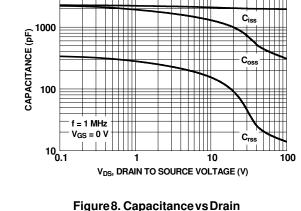


Figure 7. Gate Charge Characteristics



5000

Figure 8. Capacitance vs Drain to Source Voltage

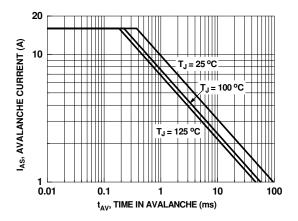


Figure 9. Unclamped Inductive Switching Capability

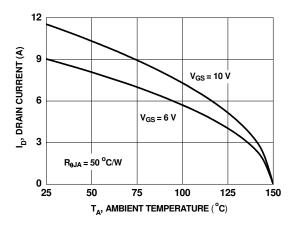


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

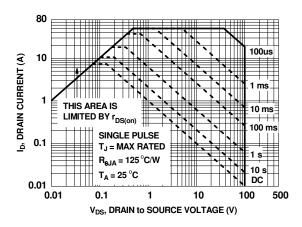


Figure 11. Forward Bias Safe Operating Area

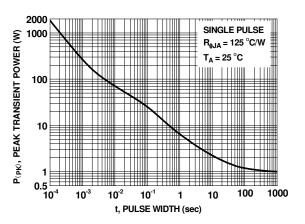


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted

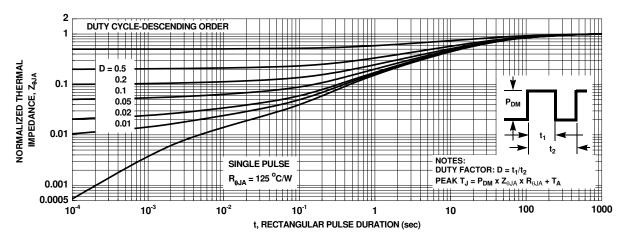
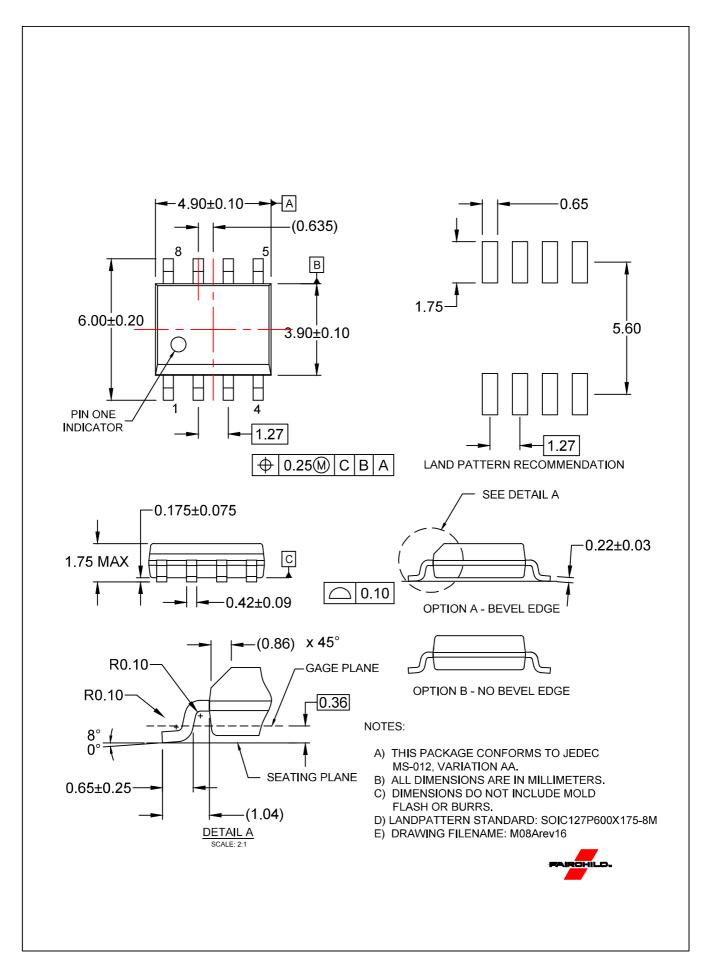


Figure 13. Junction-to-Ambient Transient Thermal Response Curve



ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative